

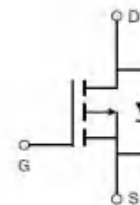
AP20P30Q

P-Channel Enhancement Mosfet



Features

- $V_{DS} = -30V$, $I_D = -35A$
 $R_{DS(ON)} < 11m\Omega$ @ $V_{GS} = -10V$ (TYP: $8.6m\Omega$)
 $R_{DS(ON)} < 18m\Omega$ @ $V_{GS} = -4.5V$ (TYP: $13m\Omega$)
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired



Schematic Diagram

Application

- PWM Applications
- Load Switch
- Power Management



Marking and pin Assignment

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
20P30Q	AP20P30Q	PDFN3X3	13 inch	-	5000

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V _{DSS}	Drain-Source Voltage		-30	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Continuous Drain Current	T _C = 25°C	-35	A
		T _C = 100°C	-24	A
I _{DM}	Pulsed Drain Current ^{note1}		-78	A
E _{AS}	Single Pulsed Avalanche Energy ^{note2}		78.8	mJ
P _D	Power Dissipation	T _A = 25°C	21.5	W
R _{θJC}	Thermal Resistance, Junction to Case		5.8	°C/W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C

Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V,I _D = -250μA	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -30V, V _{GS} = 0V,	-	-	-1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-1.0	-1.5	-2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance note3	V _{GS} =-10V, I _D =-12A	-	8.6	11	mΩ
		V _{GS} =-4.5V, I _D =-8A	-	13	18	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = -15V, V _{GS} = 0V, f = 1.0MHz	-	2800	-	pF
C _{oss}	Output Capacitance		-	346	-	pF
C _{rss}	Reverse Transfer Capacitance		-	319	-	pF
Q _g	Total Gate Charge	V _{DS} = -15V, I _D = -20A, V _{GS} = -10V	-	30	-	nC
Q _{gs}	Gate-Source Charge		-	5.3	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	7.6	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = -15V, I _D = -20A, V _{GS} =-10V, R _{GEN} =2.5Ω	-	14	-	ns
t _r	Turn-on Rise Time		-	20	-	ns
t _{d(off)}	Turn-off Delay Time		-	95	-	ns
t _f	Turn-off Fall Time		-	65	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-10	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-40	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -10A	-	-0.8	-1.2	V

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition: $T_J = 25^{\circ}\text{C}$, $V_{DD} = -20V$, $V_G = -10V$, $L = 0.5mH$, $R_G = 25\Omega$, $I_{AS} = -17A$
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

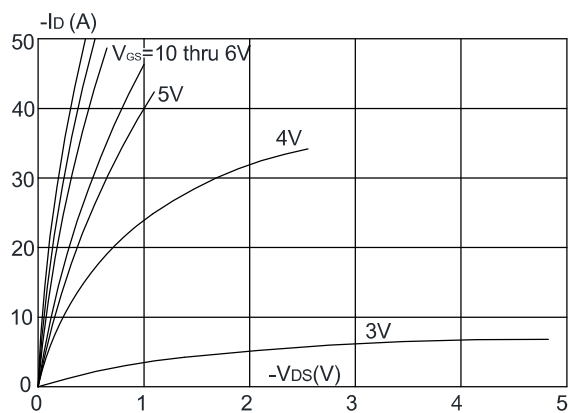


Figure 2: Typical Transfer Characteristics

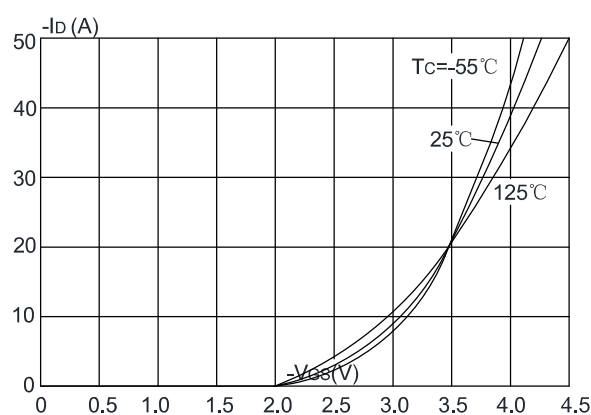


Figure 3: On-resistance vs. Drain Current

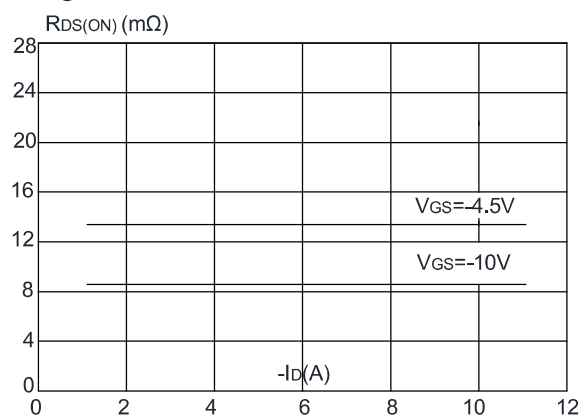


Figure 4: Body Diode Characteristics

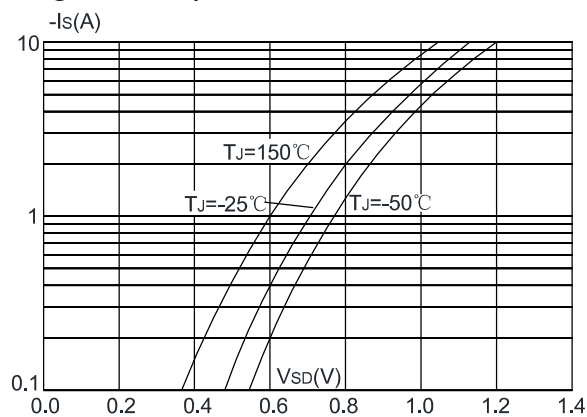


Figure 5: Gate Charge Characteristics

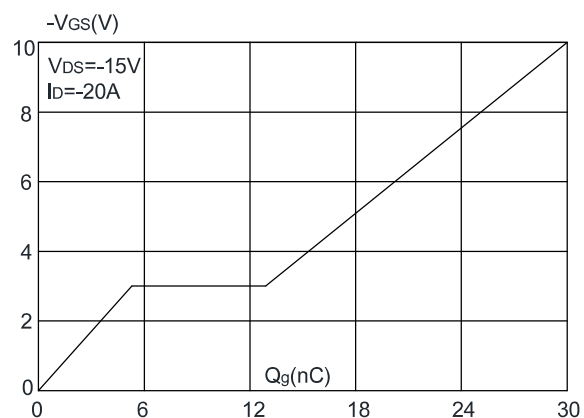


Figure 6: Capacitance Characteristics

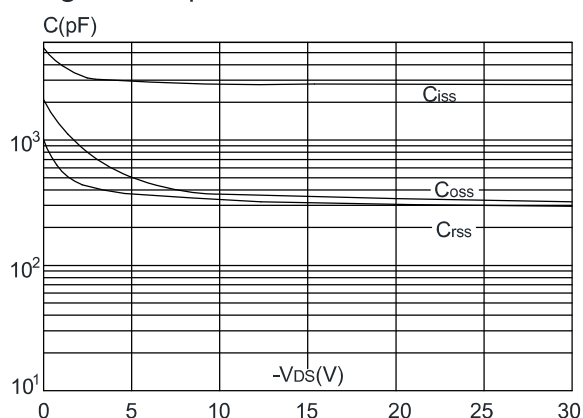


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

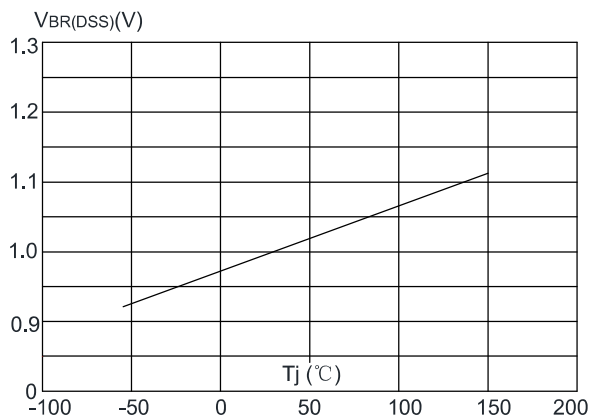


Figure 8: Normalized on Resistance vs. Junction Temperature

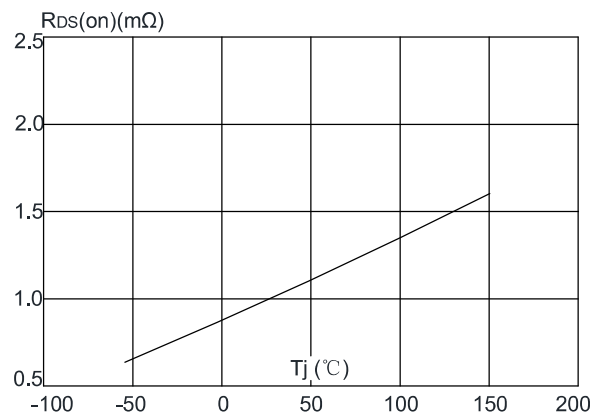


Figure 9: Maximum Safe Operating Area

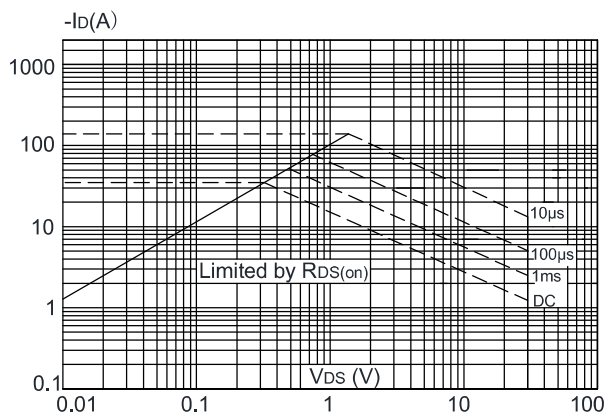


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

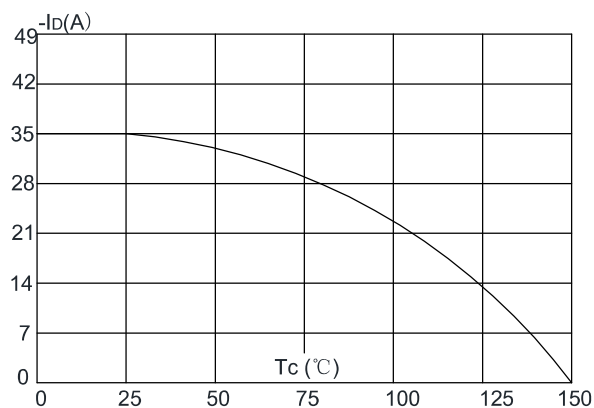
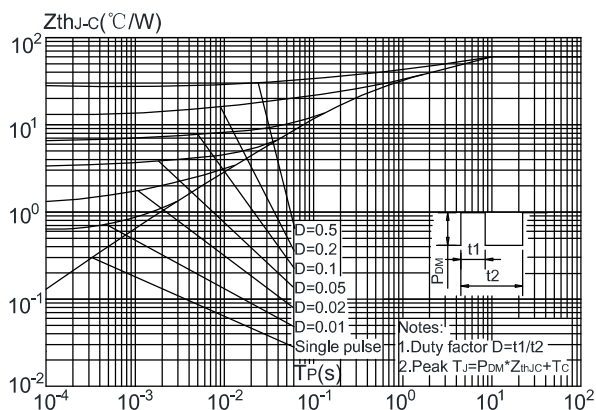
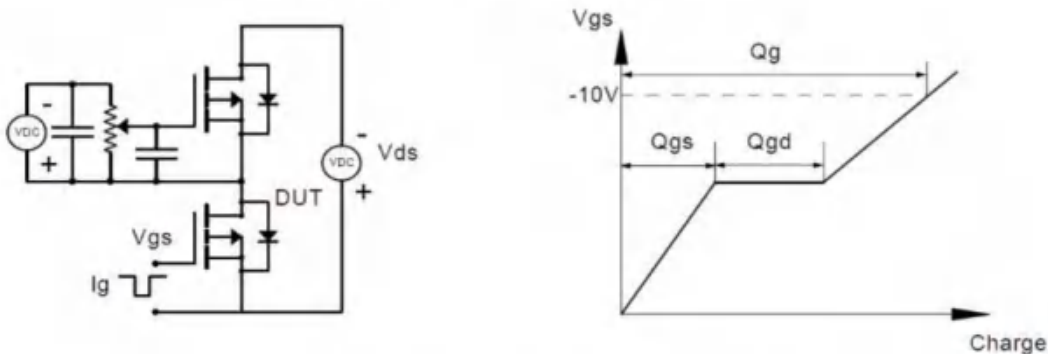


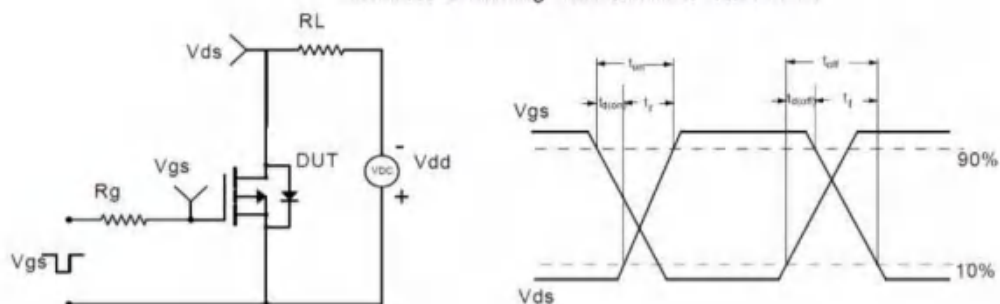
Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



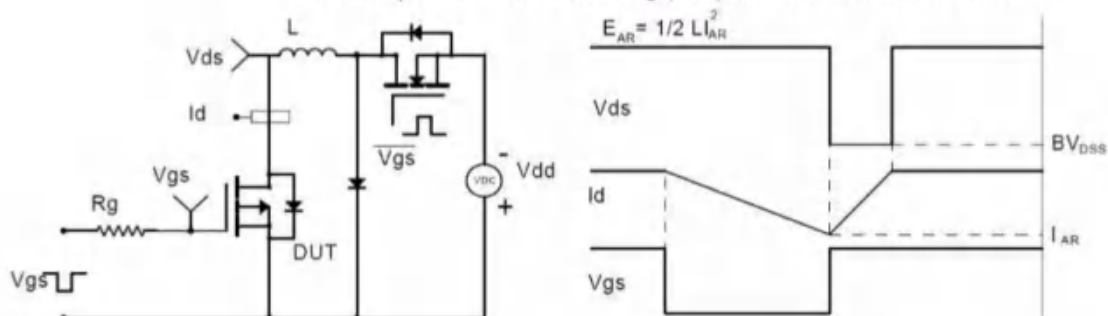
Gate Charge Test Circuit & Waveform



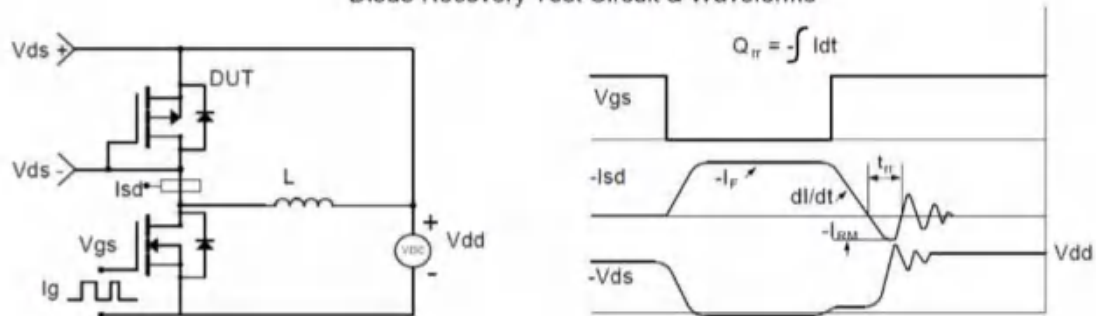
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Mechanical Data

